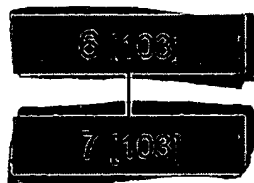
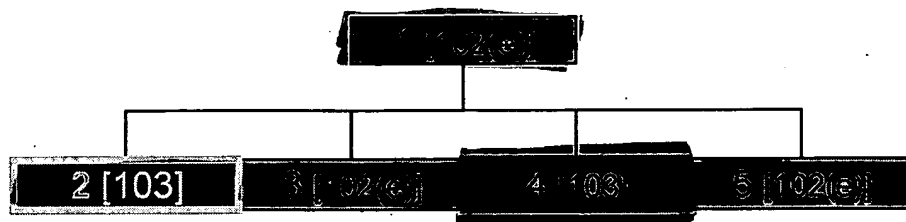


Claim Tree: 10/520856

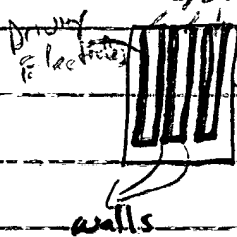


US 6802596
US 2005/0068374A1
JP-05-92561

10/524856

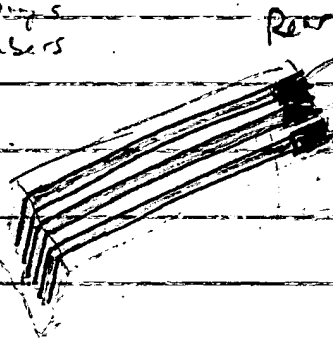
Claim Drawings

1



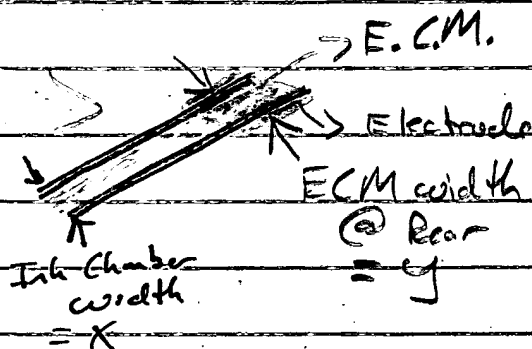
walls

→ Ink Chambers



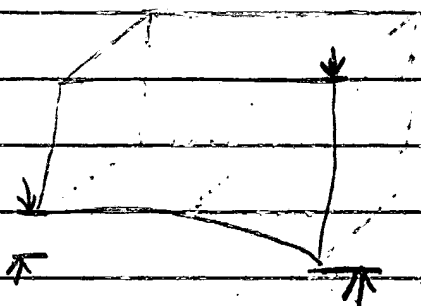
Rear

Exposed ECM



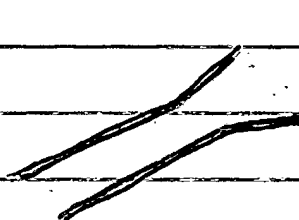
$$y > x$$

2.



Deepened IN Rear of Here

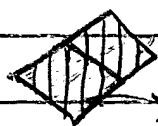
3



Rear

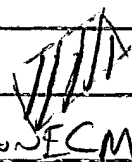
widened Portion

4



E.C.M.

→ External Circuit Connecting Electrode



Formed on ECM

5



ECM

Surface Region $\geq 3960 \mu m^2$

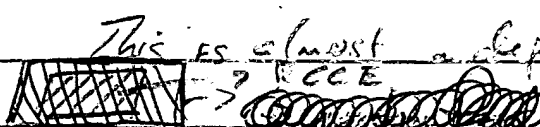
Anisotropic Conductive Adhesive

16

Same as 1 but E.C.C.E. is connected

to external circuit by pad 5 ... in anisotropic conductive material
(> How the would it 5 be connected to external circuit?)

17



This is almost a dependent claim on 1

→ Connection Pad larger than ECCE